

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

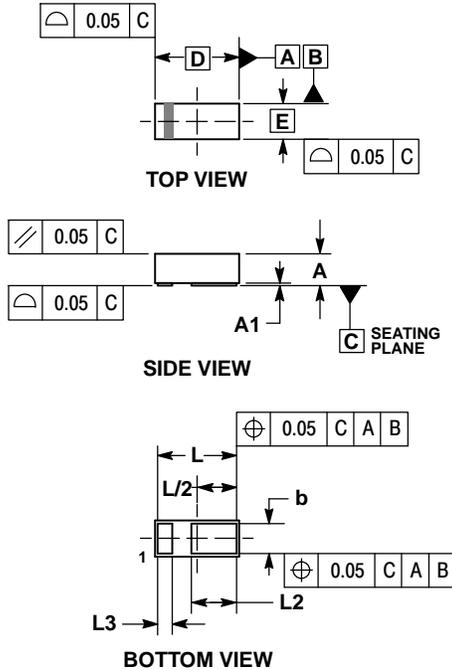
ON Semiconductor®



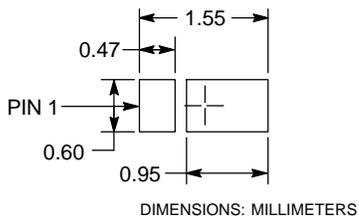
SCALE 8:1

DSN2, 1.4x0.6, 0.75P
CASE 152AD
ISSUE C

DATE 24 APR 2017



MOUNTING FOOTPRINT*



See Application Note AND8464/D for more mounting details

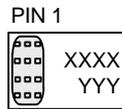
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

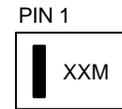
DIM	MILLIMETERS	
	MIN	MAX
A	0.25	0.31
A1	—	0.05
b	0.45	0.55
D	1.40 BSC	
E	0.60 BSC	
L	1.20	1.30
L2	0.70	0.80
L3	0.20	0.30

GENERIC MARKING DIAGRAM1*



XXXX = Specific Device Code
YYY = Year Code

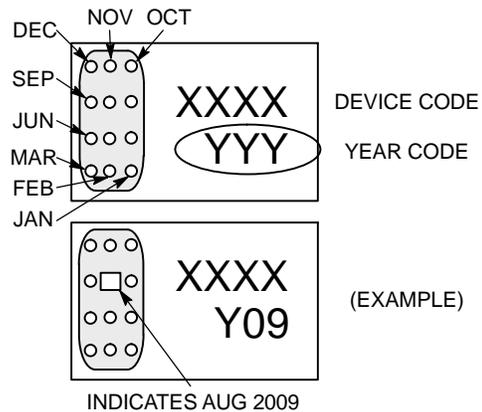
GENERIC MARKING DIAGRAM2*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

CATHODE BAND MONTH CODING



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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DSN2, 1.4X0.6, 0.75P	PAGE 1 OF 2

